

Atty. Docket No. JP920000098US1

08-31-2001



HEET

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1. Name of conveying party(ies): Takatoshi Tsujimura Osamu Tokuhira Kohichi Miwa Mitsuo Morooka Additional name(s) of conveying party(ies) attached? Yes <input type="checkbox"/> No <input checked="" type="checkbox"/> 3. Nature of conveyance: X Assignment Execution Date(s): <u>July 11, 2001, July 24, 2001, July 11, 2001, and July 11, 2001.</u>	2. Name and address of receiving party(ies): Name: International Business Machines Corporation Address: New Orchard Road Armonk, NY 10504 Additional name(s) & addresses attached? Yes <input type="checkbox"/> No <input checked="" type="checkbox"/> 4. Patent Application number(s) 09/682,002 Execution Date(s): <u>July 11, 2001, July 24, 2001, July 11, 2001, and July 11, 2001</u>
5. Name and address of party to whom correspondence concerning document should be mailed: Name: Derek S. Jennings Address: IBM Corporation Intellectual Property Law Dept. P.O. Box 218 Yorktown Heights, NY 10598	6. Total number of applications involved: 1 7. Total fee (37 CFR 3.41): \$40.00 X Charge to Deposit Account No.: <u>09-0468</u>

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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of original document.

Derek S. Jennings (Req. No. 41,473)

Name of Person Signing

Signature

August 21, 2001

Date

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PATENT

REEL: 012116 FRAME: 0252

Assignment

Whereas, we

INVENTOR
AND CITY(1) Takatoshi Tsujimura
Fujisawa-shi, Kanagawa-ken,of 2-15-26, Kugenuma-Matsugaoka,
JapanINVENTOR
AND CITY(2) Osamu Tokuhira
Gamou-gun, Shiga-ken,of 35-176, Yamazura, Ryuou-cho,
JapanINVENTOR
AND CITY(3) Kohichi Miwa
Yokohama-shi, Kanagawa-ken,of 6-1-C503, Enokigaoka, Aoba-ku,
JapanINVENTOR
AND CITY(4) Mitsuo Morooka
Kawasaki-shi, Kanagawa-ken,of 3-11-116, Saginuma, Miyamae-ku,
Japan

TITLE

have invented certain improvements in
ACTIVE MATRIX SUBSTRATE AND MANUFACTURING METHOD THEREOFDATES THAT
INVENTORS
SIGNED THE
DECLARATION

and executed, respectively, a United States patent application therefor on

(1) 7/11/2001 2001, and (2) 07/24 2001,
(3) 7/11/2001 2001, and (4) 7/11/2001 2001.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said applications to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed

CITY AND
DATE(1) at Yamato
on 7/11/2001,Takatoshi Tsujimura

SIGNATURE

(Takatoshi

Tsujimura) INVENTOR

FIRST NAME

MIDDLE INITIAL

LAST NAME

CITY AND
DATE(2) at Yasu
on 7/24/2001,Osamu Tokuhira

SIGNATURE

(Osamu

Tokuhira) INVENTOR

FIRST NAME

MIDDLE INITIAL

LAST NAME

PATENT

REEL: 012116 FRAME: 0253

CITY AND DATE (3) at on Yamato 7/11/2001, Kohichi Miwa SIGNATURE
(Kohichi Miwa) INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME

CITY AND DATE (4) at on Yamato 7/11/2001, Mitsuo Morooka SIGNATURE
(Mitsuo Morooka) INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME